



Product data sheet

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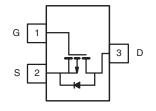


NTR4101PT1G-MS

Semiconductor Compiance



SOT-23



Features

- -20V,-3.2A, RDS(ON) =70mΩ@VGS = -4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

BVDSS	RDSON	ID
-20V	$70 \text{m}\Omega$	-3.2A

Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _{GS}	Gate-Source Voltage	±12	V
	Drain Current – Continuous (T _C =25°C)	-3.2	A
ID	Drain Current – Continuous (T _C =100°C)	-2.0	A
I _{DM}	Drain Current – Pulsed ¹	-12.8	A
D	Power Dissipation (T _c =25°C)	1.56	W
Po	Power Dissipation – Derate above 25°C	0.012	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	R _{0JA} Thermal Resistance Junction to ambient		80	°C/W





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Electrical Characteristics (TJ=25 °C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-20			V
$\triangle BV_{DSS} \triangle T_J$	BV _{DSS} Temperature Coefficient	Reference to 25°C ,I _D =-1mA		-0.01		V/°C
	Durain Source Looke no Cumont	V_{DS} =-20V , V_{GS} =0V , T_{J} =25°C			-1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-16V , V _{GS} =0V , T _J =125°C			-10	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12V$, $V_{DS}=0V$			±10	uA

On Characteristics

gfs	Forward Transconductance	V _{DS} =-10V , I _S =-1A		2.2		S
∆V _{GS(th)}	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		3		mV/°C
V _{GS(th)}	Gate Threshold Voltage		-0.3	-0.7	-1.2	V
1403(011)		V _{GS} =-2.5V , I _D =-2A		90	120	1115.2
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V , I _D =-3A		70	85	mΩ

Dynamic and switching Characteristics

Qg	Total Gate Charge ^{2,3}		 4.8	
Q _{gs}	Gate-Source Charge ^{2,3}	V _{DS} =-10V , V _{GS} =-4.5V , I _D =-3A	 0.5	 nC
Q _{gd}	Gate-Drain Charge ^{2,3}		 1.9	
T _{d(on)}	Turn-On Delay Time ^{2 , 3}		 3.5	
Tr	Rise Time ^{2 , 3}	V_{DD} =-10V , V_{GS} =-4.5V , R_{G} =25 Ω	 12.6	 nS
T _{d(off)}	Turn-Off Delay Time ^{2 , 3}	I _D =-1A	 32.6	 115
T _f	Fall Time ^{2 , 3}		 8.4	
C _{iss}	Input Capacitance		 550	
C _{oss}	Output Capacitance	V _{DS} =-10V , V _{GS} =0V , F=1MHz	 65	 pF
C _{rss}	Reverse Transfer Capacitance		 55	

Drain-Source Diode Characteristics and Maximum Ratings						
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current				-3.2	А
I _{SM}	Pulsed Source Current	V _G =V _D =0V , Force Current			-6.4	А
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =-1A , T_{J} =25 $^{\circ}$ C			-1.2	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

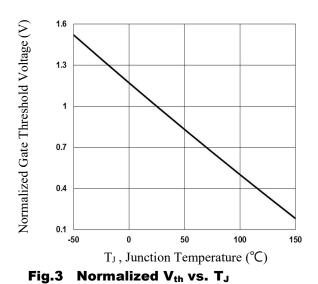
2. 3. The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%.$

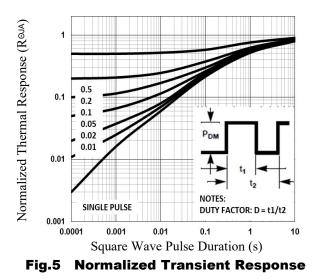
Essentially independent of operating temperature.

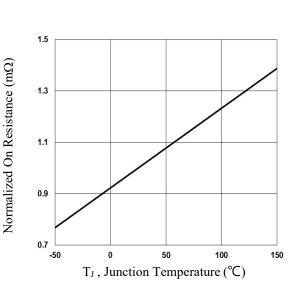


(Y) r_{-}^{4} r_{-}^{4}









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HF

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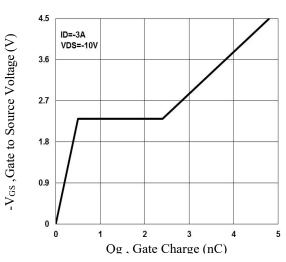
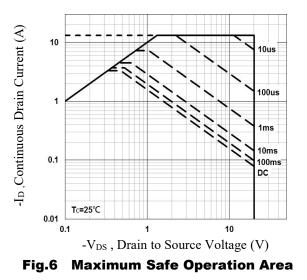


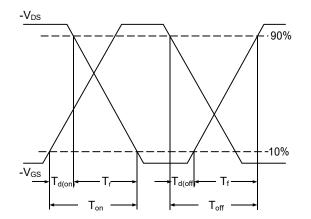
Fig.4 Gate Charge Waveform





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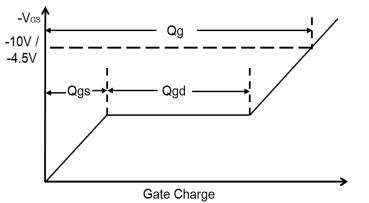




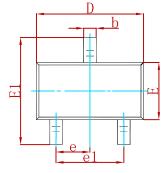
Fig.8 Gate Charge Waveform

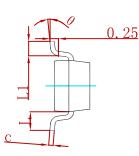


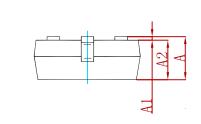
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PACKAGE MECHANICAL DATA

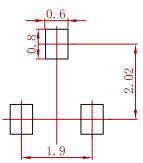






Symbol	Dimensions	In Millimeters	Dimension	s in inches
Symbol	Min	Max	Min	Max
А	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
С	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
е	0.950) TYP	0.037	7 TYP
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022	2 REF
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

Controlling dimension:in millimeters.
General tolerance:± 0.05mm.
The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
NTR4101PT1G-MS	SOT-23	3000



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